

KEYFLEX BT S-5035

>TPEE<

IMDS ID : 32326853

Properties	Value	Unit	Standard
Mechanical properties			
Tensile Stress – 5% Strain	9.8	MPa	ISO 527-1/-2
Tensile Stress – 10% Strain	12.4	MPa	ISO 527-1/-2
Tensile Stress – 50% Strain	14.7	MPa	ISO 527-1/-2
Tensile Stress(Break)	33	MPa	ISO 527-1/-2
Tensile Strain(Break)	470	%	ISO 527-1/-2
Flexual Modulus – 23°C	320	MPa	ISO 178
Hardness, Durometer 15s	52		ISO 868
Hardness, Durometer Maximum	55		ISO 868
Izod Impact, notched, 80*10*4, -40°C	NB	kJ/m ²	ISO 180/1A
Izod Impact, notched, 80*10*4, +23°C	NB	kJ/m ²	ISO 180/1A
Charpy Impact, notched, 80*10*4, -40°C	NB	kJ/m ²	ISO 179/1eA
Charpy Impact, notched, 80*10*4, +23°C	NB	kJ/m ²	ISO 179/1eA
Tear Strength (Method B, unnicked)	141	kN/m	ISO 34
Thermal properties			
Melt volume–flow rate	15	cm ³ /10min	ISO 1133
Temperature/Load–2.16kg	240	°C/kg	ISO 1133
Temp. of deflection under load (0.45 MPa)	50	°C	ISO 75-1/-2
Melting Temperature(10°C/10min)	225	°C	ISO 11357-1/-3
Glass transition Temperature	-45	10°C/min	ISO 11357-1/-3
Vicat softening temperature (50°C/h 10N)	170	°C	ISO 306
Vicat softening temperature (50°C/h 50N)	55	°C	ISO 306
Electrical properties			
Surface resistivity	>1E12	Ohm	IEC 60093
Volume resistivity	>1E12	Ohm*m	IEC 60093
Relative permittivity (1MHz)	4.4	-	IEC 60250
Relative permittivity (700 MHz)	1.5	-	IEC 60250
Dissipation factor (1MHz)	230	E-4	IEC 60250
Dissipation factor (700 MHz)	1130	E-4	IEC 60250
Electric strength, Short Time, 1mm	24	kV/mm	IEC 60243-1
Comparative tracking index	600	-	IEC 60112
Other properties			
Density	1170	kg/m ³	ISO 1183
Humidity absorption–Equilibrium 50%RH	0.2	%	Sim. to ISO 62
Water absorption – Immersion 24h	0.6	%	Sim. to ISO 62
Water absorption – Saturation, immersed	0.6	%	Sim. to ISO 62
Mold Shrinkage(normal)	1.6	%	ISO 2577, 294-4
Mold Shrinkage(parallel)	1.5	%	ISO 2577, 294-4
Test specimen production			
Injection Molding, melt temperature	245	°C	ISO 294
mold temperature – range	40–60	°C	ISO 10724
mold temperature – optimum	50	°C	ISO 10724
Flammability			
Flammability Classification	HB	-	UL94
Oxygen Index	22	-	ISO 4589

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Injection Molding Guideline

Conditions		Unit	Value
Preliminary Drying Temperature		°C	100~120
Preliminary Drying Time		hrs	3 ~ 4
Cylinder Temperature	Rear	°C	215 ~ 225
	Middle	°C	220 ~ 230
	Front	°C	225 ~ 235

1) The above is a table of standard processing conditions and subject to change dependent upon shapes of injection molds.

Drying

If the resin has an excessively high moisture content, this can result in surface defects, i.e. silver streaks, and impaired properties of molded parts. To ensure optimum part performance and prevent surface defects, TEPP resins must be dried prior to processing, and moisture level maintained less than 0.1%. A dehumidifying hopper dryer is highly recommended.

The hopper dryer should be preheated to the suggested drying temperature before the pellets are loaded

Holdind Time/ Pressure

Volume shrinkage takes place when the molded part cools in the mold. Holding pressure serves to offset the volume shrinkage. Holding pressure should be maintained until the gate has "frozen". The required holding pressure time can be determined by checking the weight of the molded part.

■ Please contact EP team for any questions or requirements of detail information about LG EP products.